# 2SD1263, 2SD1263A

## Silicon NPN triple diffusion planar type

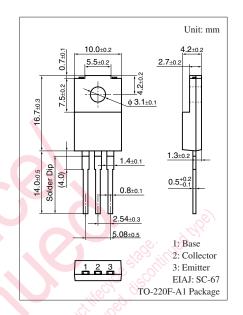
### For power amplification

#### ■ Features

- High collector-base voltage (Emitter open) V<sub>CBO</sub>
- Full-pack package which can be installed to the heat sink with one screw

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage	2SD1263	V <sub>CBO</sub>	350	V
(Emitter open)	2SD1263A		400	
Collector-emitter voltage	2SD1263	V <sub>CEO</sub>	250	V
(Base open)	2SD1263A		300	
Emitter-base voltage (Col	$V_{EBO}$	5	V	
Collector current	$I_C$	0.75	A	
Peak collector current	$I_{CP}$	1.5	A	
Collector power	$T_C = 25^{\circ}C$	P <sub>C</sub>	35	W
dissipation			2.0	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	



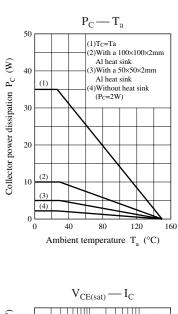
## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

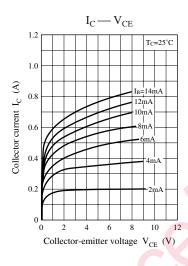
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage	2SD1263	V <sub>CEO</sub>	$I_C = 30 \text{ mA}, I_B = 0$	250			V
(Base open)	2SD1263A		J'incre HAP	300			
Base-emitter voltage		V <sub>BE</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ A}$			1.5	V
Collector-emitter cutoff	2SD1263	I <sub>CES</sub>	$V_{CE} = 350 \text{ V}, V_{BE} = 0$			1	mA
current (E-B short)	2SD1263A		$V_{CE} = 400 \text{ V}, V_{BE} = 0$			1	
Collector-emitter cutoff	2SD1263	I <sub>CEO</sub>	$V_{CE} = 150 \text{ V}, I_{B} = 0$			1	mA
current (Base open)	2SD1263A	*SLOIL	$V_{CE} = 200 \text{ V}, I_{B} = 0$			1	
Emitter-base cutoff current (Co	llector open)	I <sub>EBO</sub>	$V_{EB} = 5 \text{ V}, I_{C} = 0$			1	mA
Forward current transfer rat	io	h <sub>FE1</sub> *	$V_{CE} = 10 \text{ V}, I_{C} = 0.3 \text{ A}$	40		250	_
	6.	h <sub>FE2</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ A}$	10			
Collector-emitter saturation	voltage	V <sub>CE(sat)</sub>	$I_C = 1 A, I_B = 0.2 A$			1	V
Transition frequency	B	$f_T$	$V_{CE} = 5 \text{ V}, I_C = 0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz
Turn-on time		t <sub>on</sub>	$I_C = 1 A$ , $I_{B1} = 0.1 A$ , $I_{B2} = -0.1 A$		0.5		μs
Storage time		t <sub>stg</sub>	$V_{CC} = 50 \text{ V}$		2.0		μs
Fall time		$t_{\rm f}$			0.5		μs

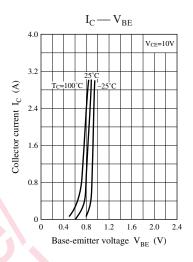
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

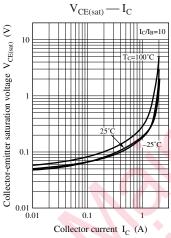
#### 2. \*: Rank classification

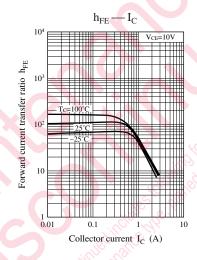
Rank	R	Q	Р
$h_{FE1}$	40 to 90	70 to 150	120 to 250

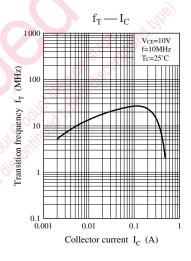


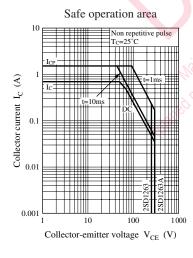


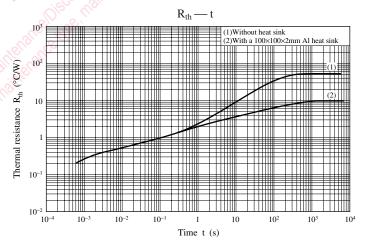












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